COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

BOARD #: TIDA-01330
REV: E1
SUN REV: Not In VersionControl

TID #: TIDA-01330

PLOT NAME = Top Assembly Drawing
GENERATED: 2/14/2017 12:05:09 PM
TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>BOARD #: TIDA-01330</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>GENERATED: 2/14/2017 12:05:11 PM</td>
<td>TEXAS INSTRUMENTS</td>
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